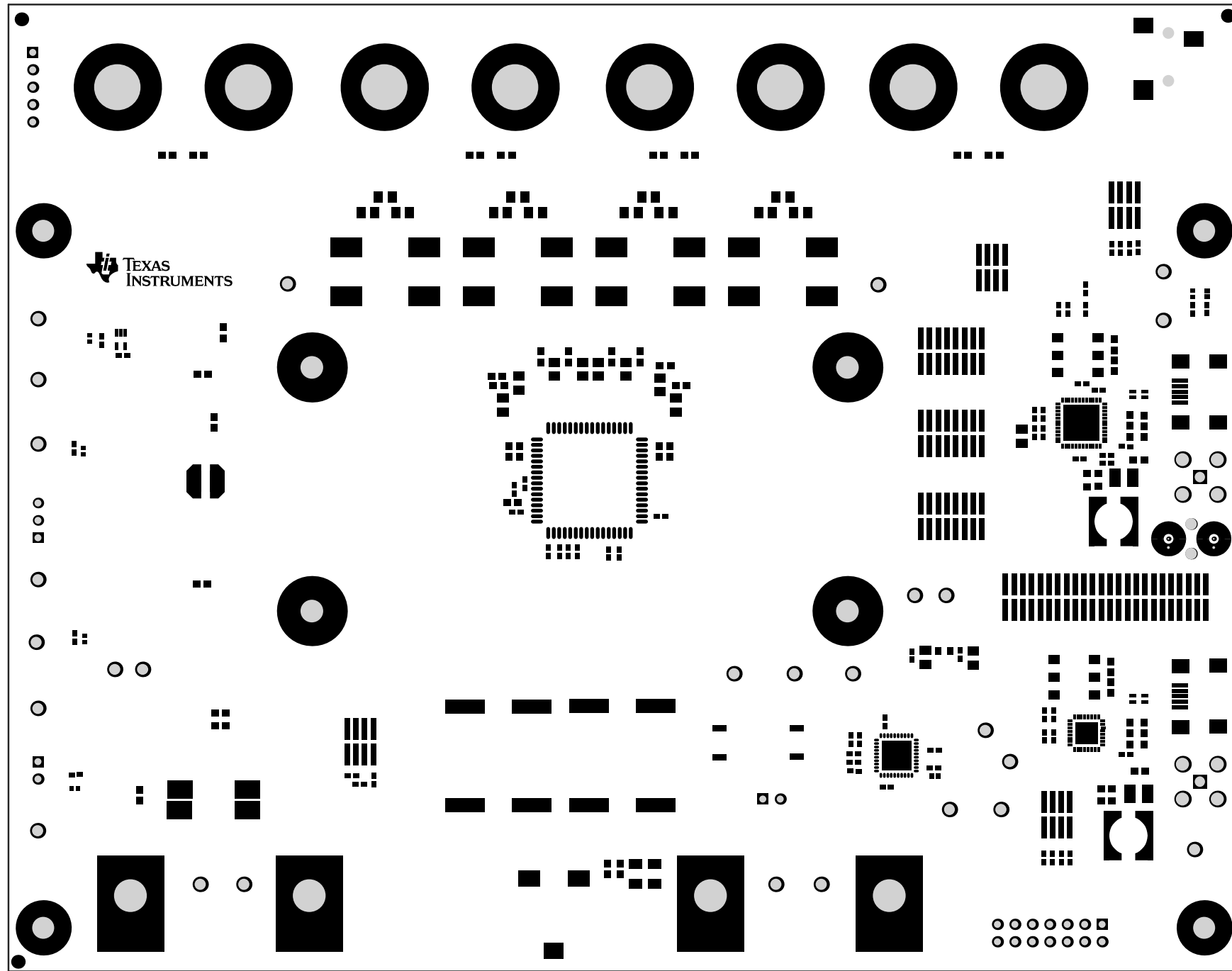
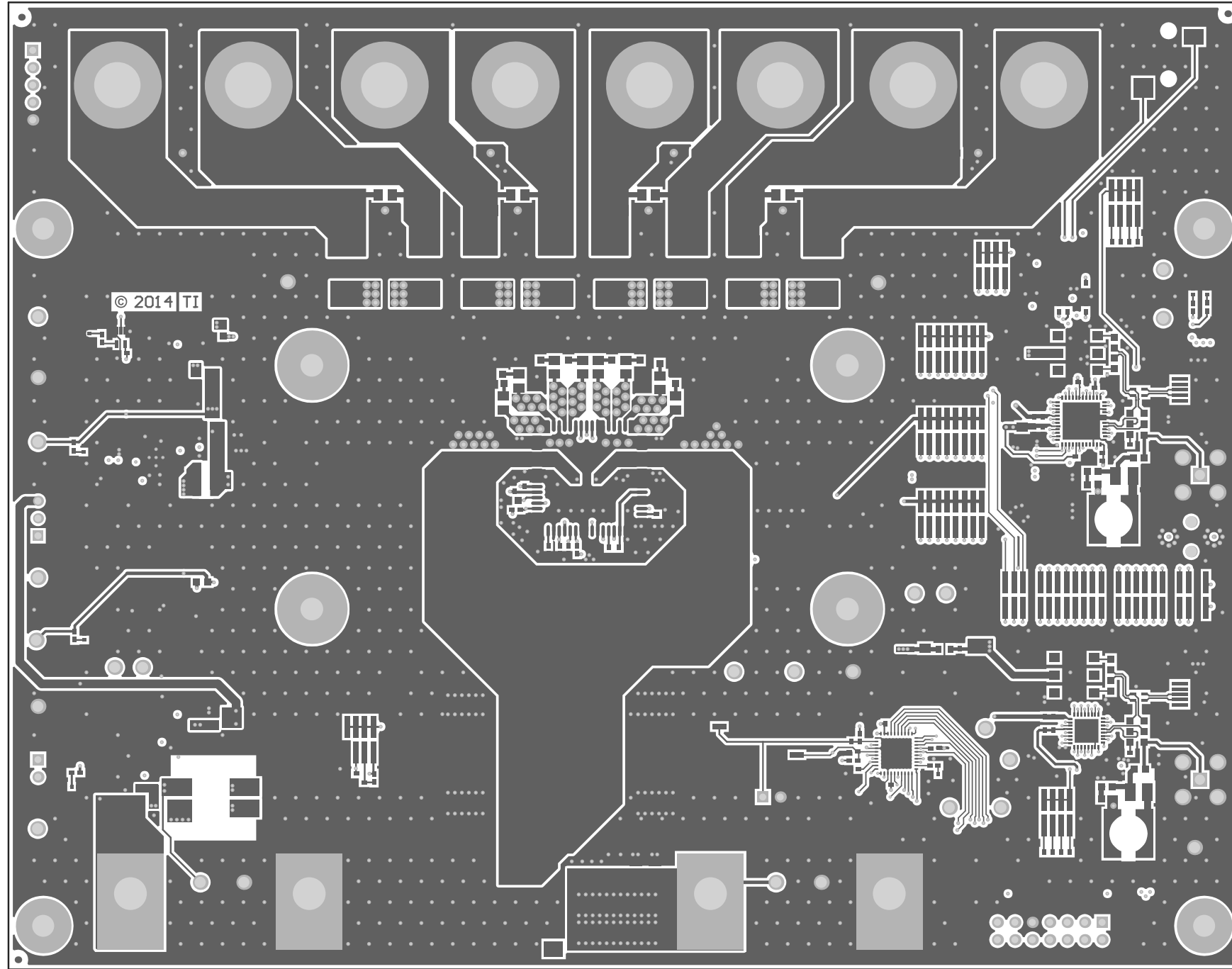


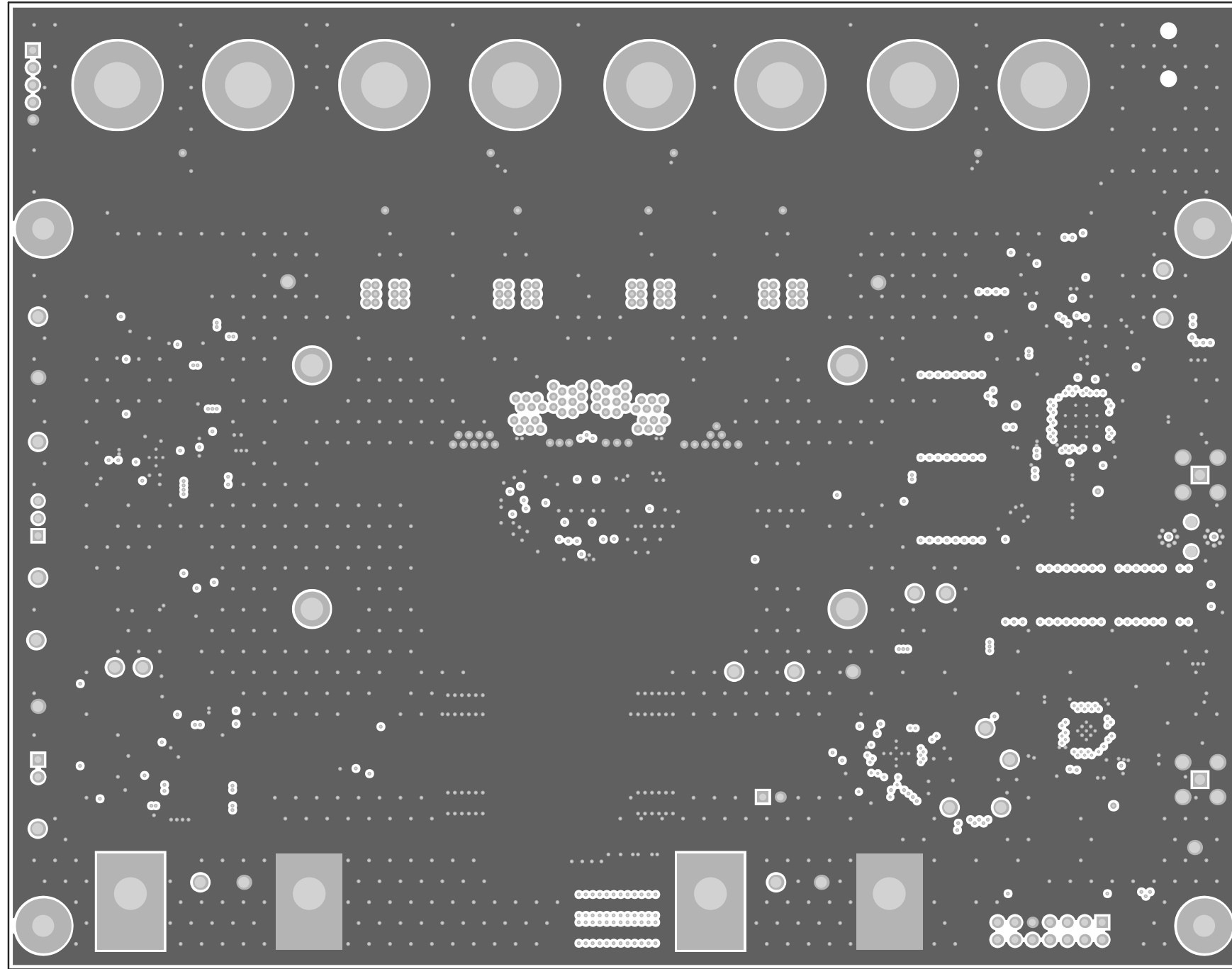
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/10/2014 11:14:37 AM	TEXAS INSTRUMENTS	



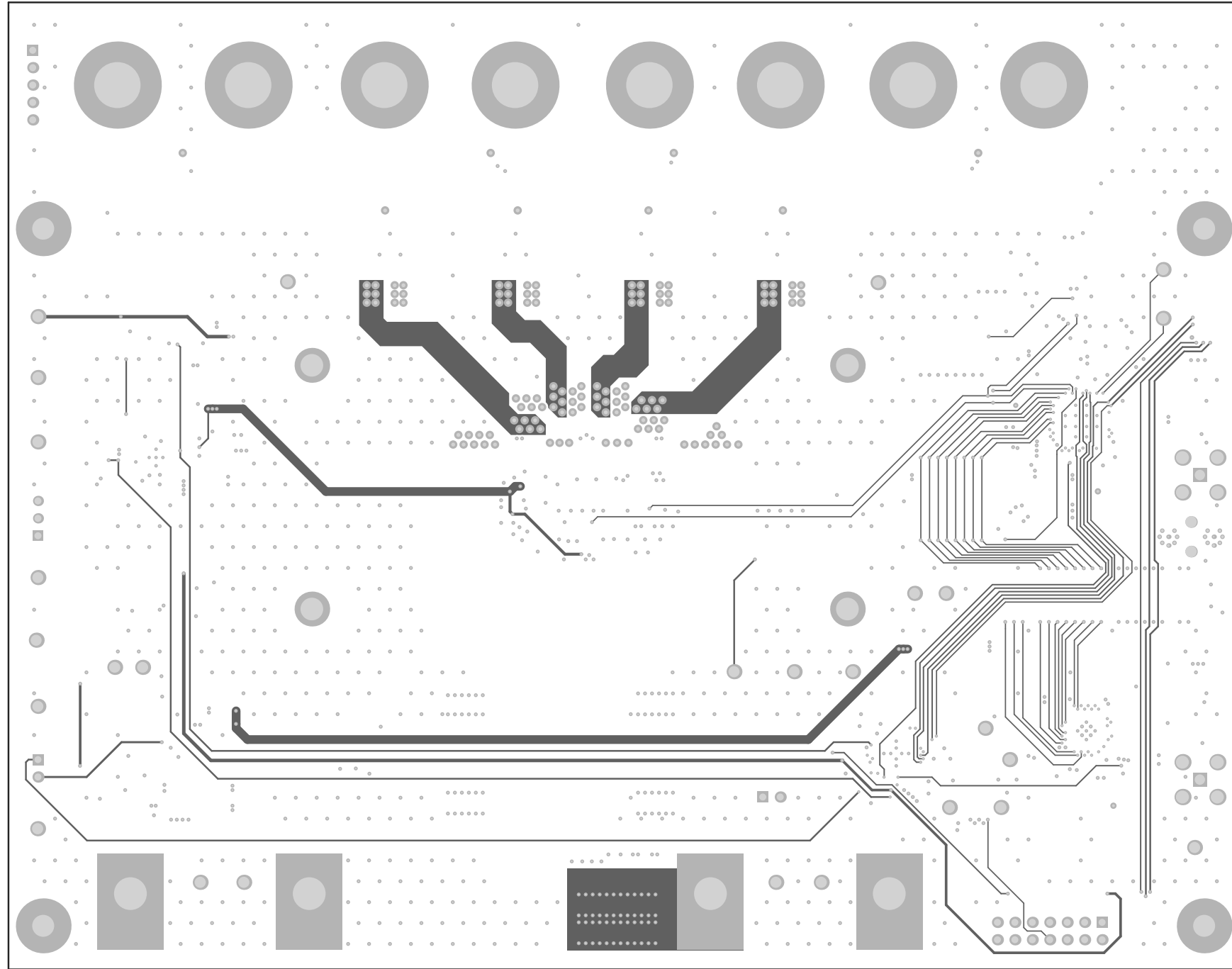
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/10/2014 11:14:38 AM	TEXAS INSTRUMENTS	



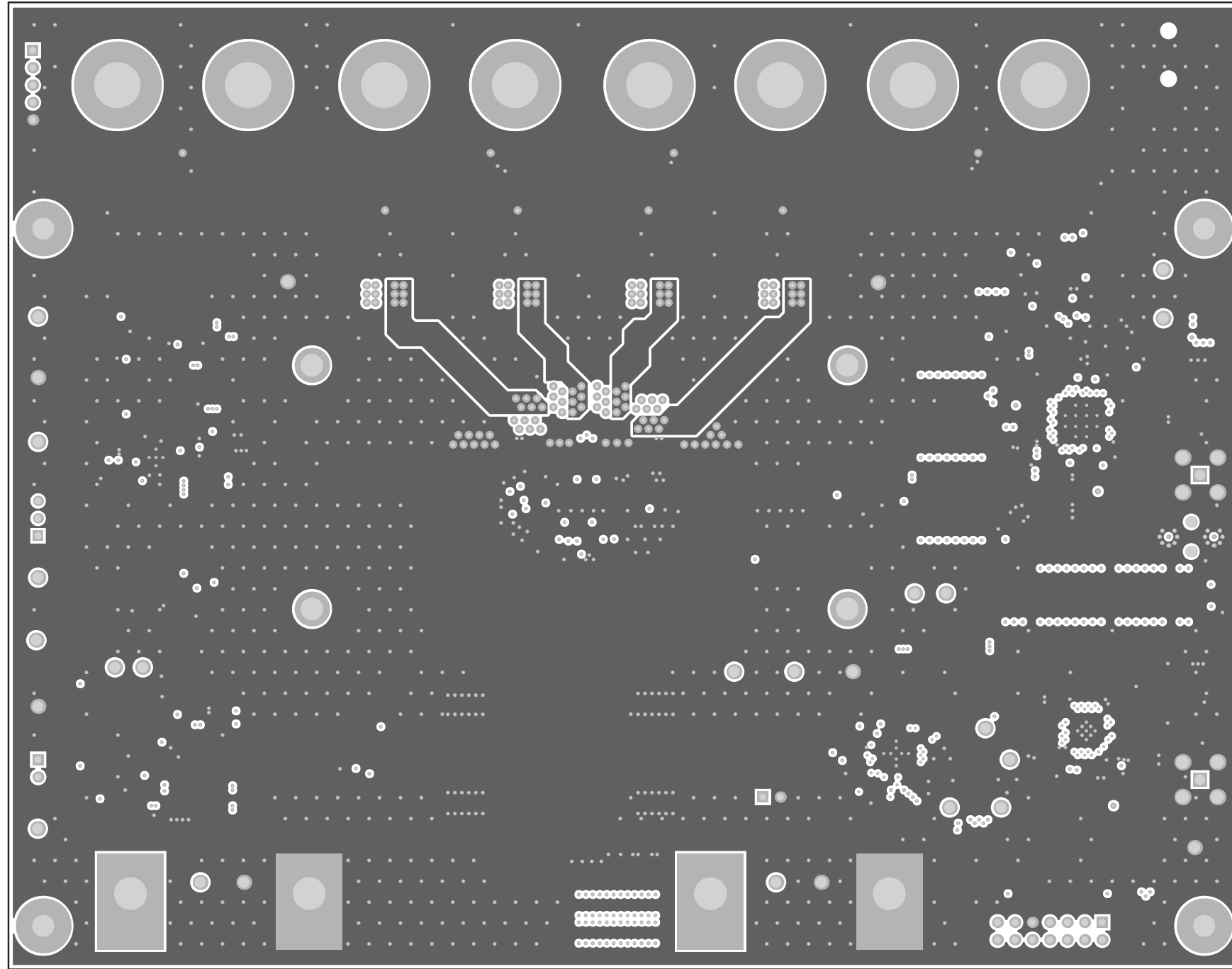
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 7/10/2014 11:14:39 AM	TEXAS INSTRUMENTS	



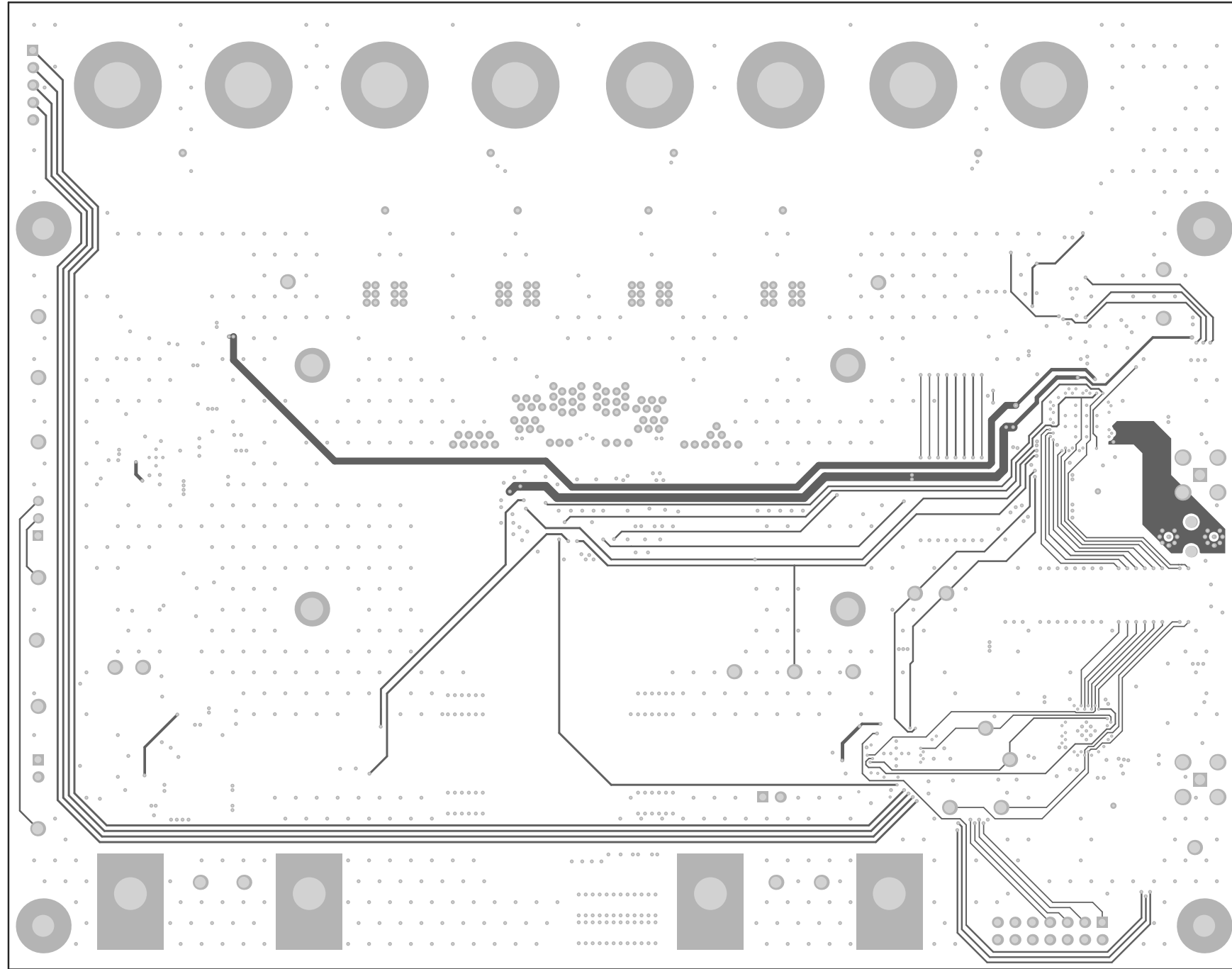
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1-GND			
PLOT NAME = MidLayer1	GENERATED : 7/10/2014 11:14:39 AM	TEXAS INSTRUMENTS	



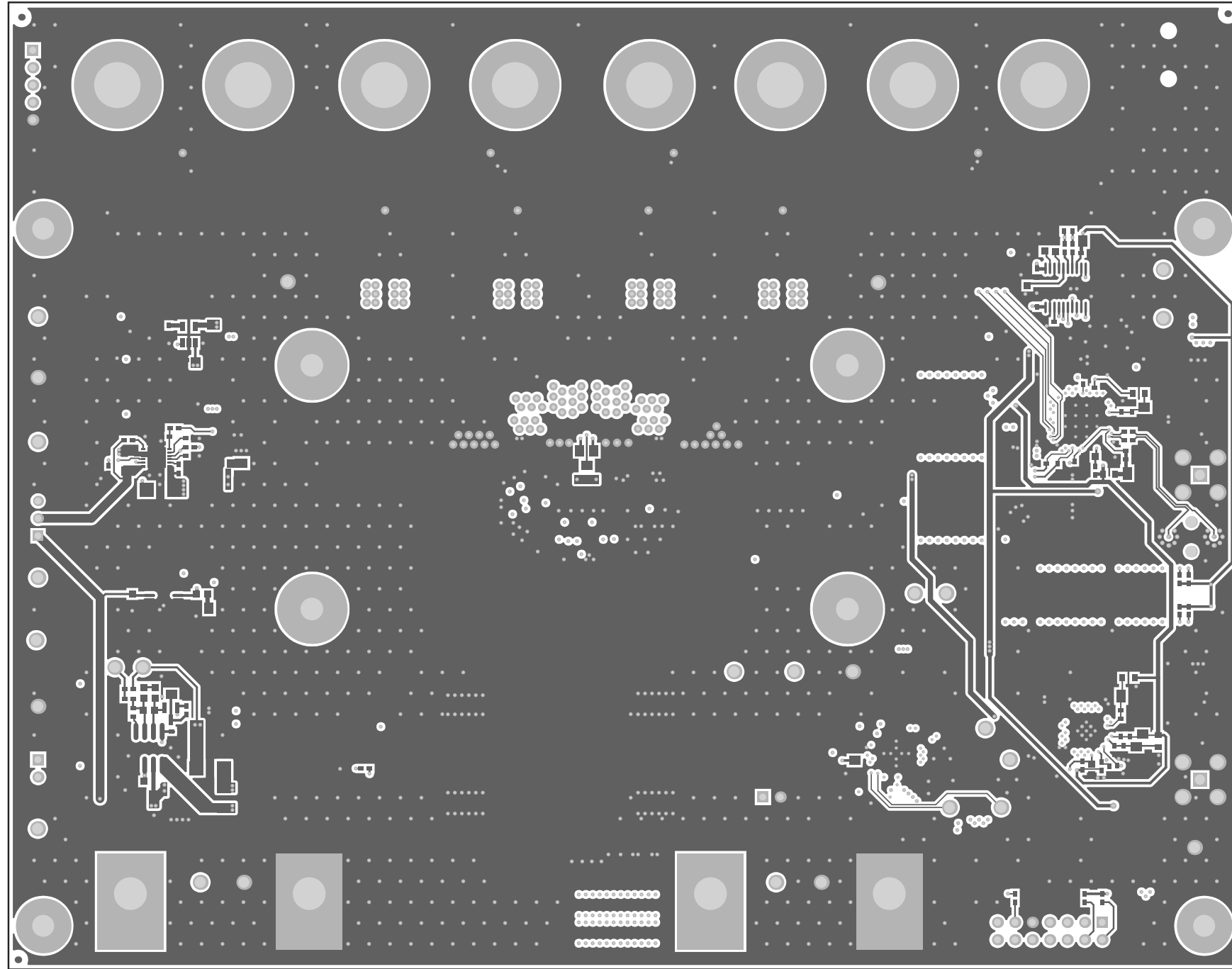
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2-HiSp			
PLOT NAME = MidLayer2	GENERATED : 7/10/2014 11:14:40 AM	TEXAS INSTRUMENTS	



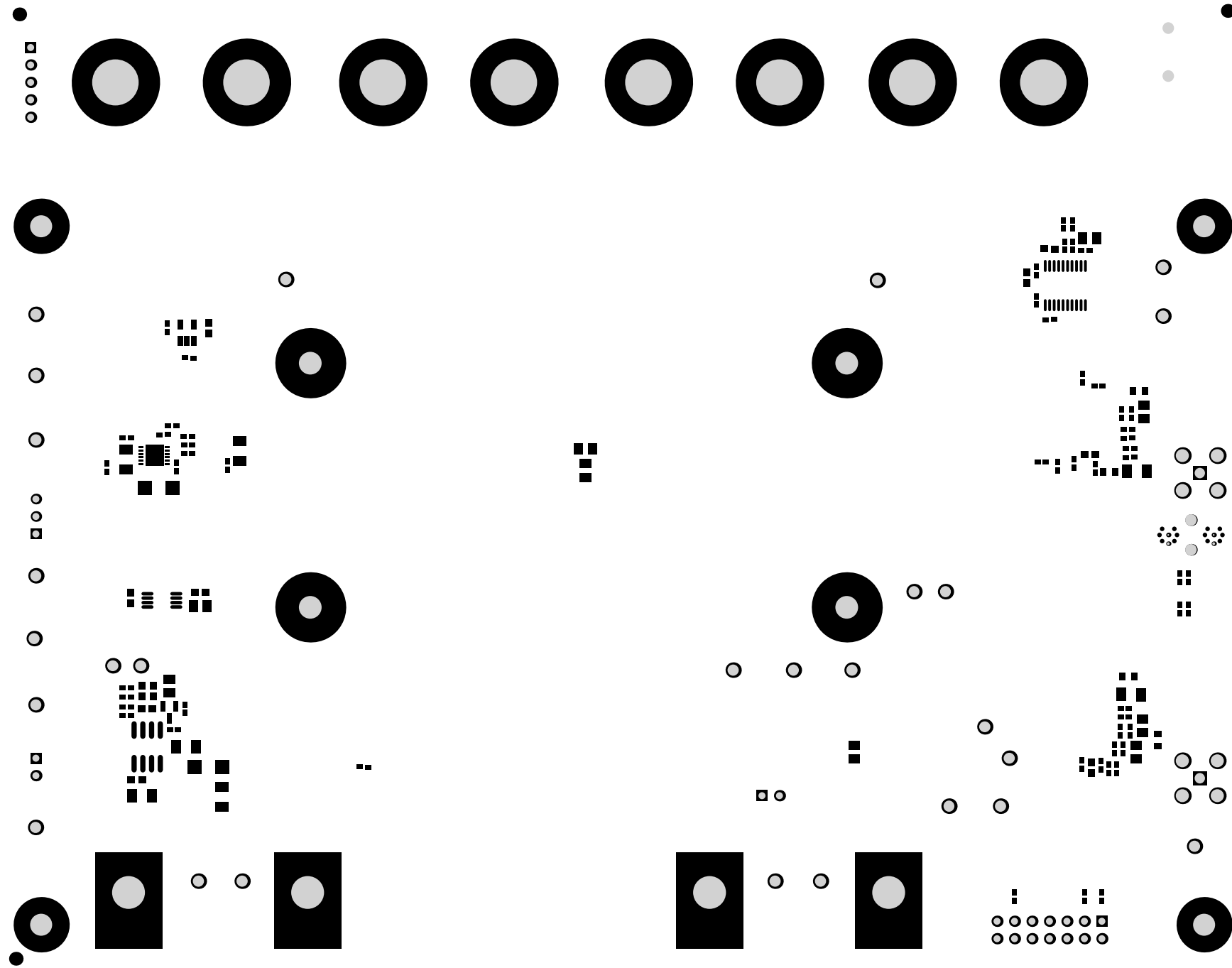
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer3-GND			
PLOT NAME = MidLayer3	GENERATED : 7/10/2014 11:14:41 AM	TEXAS INSTRUMENTS	



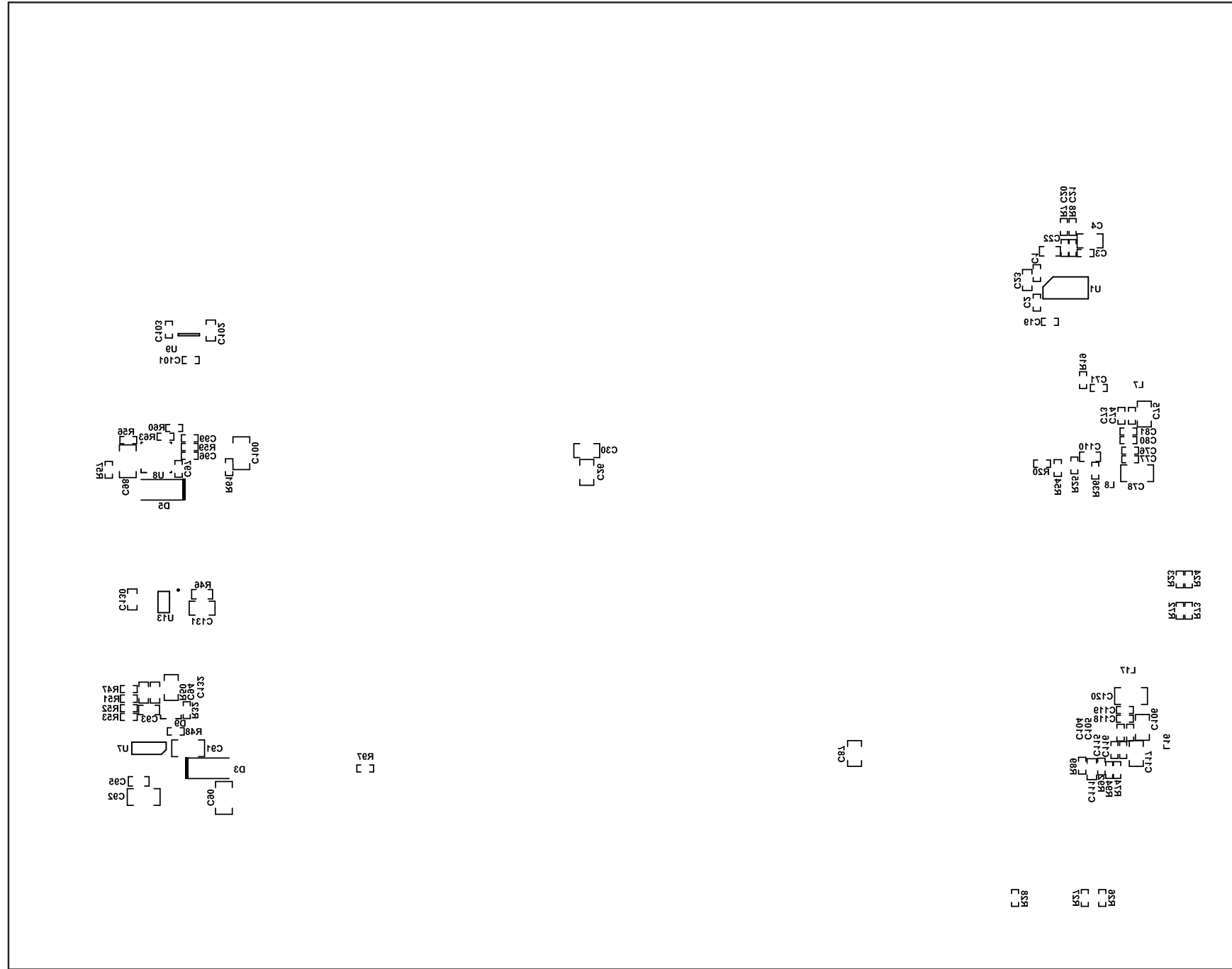
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer4			
PLOT NAME = MidLayer4	GENERATED : 7/10/2014 11:14:41 AM	TEXAS INSTRUMENTS	



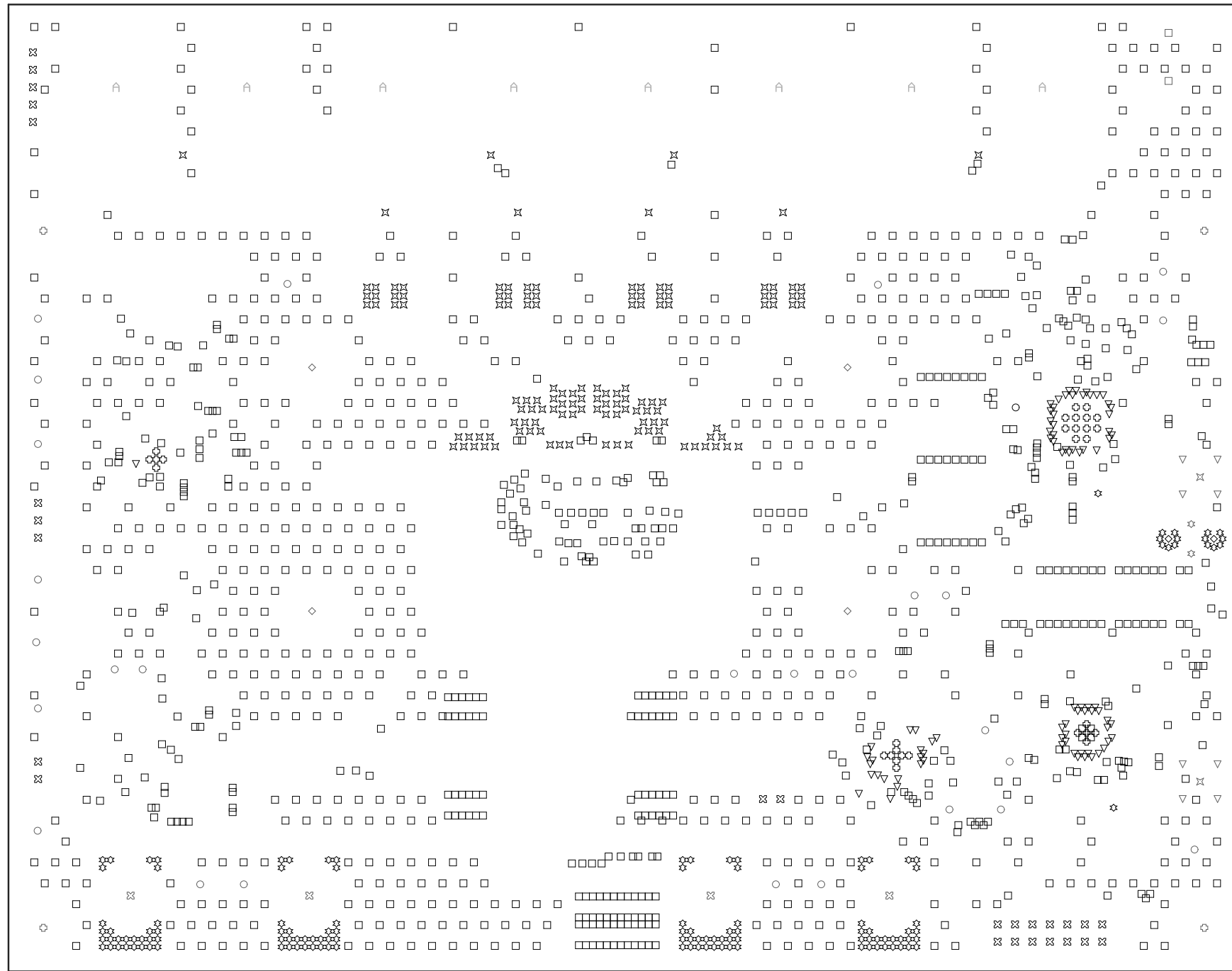
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/10/2014 11:14:42 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/10/2014 11:14:42 AM	TEXAS INSTRUMENTS	



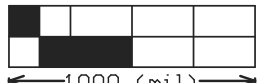
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 7/10/2014 11:14:43 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
⊕	30	7.874mil (0.2mm)	PTH	Round
∇	81	8mil (0.203mm)	PTH	Round
◇	2	9.842mil (0.25mm)	PTH	Round
□	1180	10mil (0.254mm)	PTH	Round
○	1	12mil (0.305mm)	PTH	Round
✱	128	16mil (0.406mm)	PTH	Round
✱	128	22mil (0.559mm)	PTH	Round
✱	26	40mil (1.016mm)	PTH	Round
✱	2	59.055mil (1.5mm)	PTH	Round
○	27	63mil (1.6mm)	PTH	Round
✱	2	66.929mil (1.7mm)	PTH	Round
□	2	66.929mil (1.7mm)	NPTH	Round
∇	8	74.803mil (1.9mm)	PTH	Round
⊕	4	125.984mil (3.2mm)	PTH	Round
◇	4	130mil (3.302mm)	PTH	Round
✱	4	188mil (4.775mm)	PTH	Round
A	8	265mil (6.731mm)	PTH	Round
1637 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/10/2014 11:14:43 AM	TEXAS INSTRUMENTS	



←1000 (mil)→

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 7/10/2014 11:14:46 AM	TEXAS INSTRUMENTS	

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